

Application No.: 10/058,664

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**AMENDMENTS TO THE CLAIMS**

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claim 1 (currently amended): A semiconductor laser package comprising:

an island member formed of metal, including a base plane and a block member protruding in a direction substantially perpendicular to said base plane,

a plurality of leads ~~[[lead]]~~,

a one-piece resin member molded integrally with said island member and said lead so as to fix a relative position relationship between said island member and all said plurality of leads ~~[[lead]]~~,

a laser chip fixed at said block member so as to enable emission of a laser beam in a direction substantially perpendicular to said base plane, and

a light receiving unit directly fixed at said resin member.

Claim 2 (original): The semiconductor laser package according to claim 1, wherein said resin member has a light receiving unit attaching plane substantially parallel to said base plane, and said light receiving unit is mounted at said light receiving unit attaching plane.

Claim 3 (original): The semiconductor laser package according to claim 1, wherein a heat radiator is fixed at said block unit, and said laser chip is fixed to said block unit so as to form contact with said heat radiator.

Claim 4 (original): The semiconductor laser package according to claim 3, wherein said heat radiator comprises light receiving means.

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Claim 5 (original): The semiconductor laser package according to claim 1, wherein a hologram element is arranged located on an optical path of a laser beam emitted from said laser chip.

Claim 6 (original): The semiconductor laser package according to claim 1, comprising a cover to enclose said laser chip and said light receiving unit.

Claim 7 (currently amended): A fabrication method of a semiconductor laser package comprising:

a resin member molding step of molding a one-piece resin member integrally with an island member formed of metal, including a base plane and a block member protruding substantially in a direction of a normal line to said base plane, and all of a plurality of leads ~~a lead integrally with resin~~ so as to fix a relative position relationship between said island member and all said plurality of leads [[lead]],

a laser chip attaching step of fixing a laser chip at said block member so as to enable emission of a laser beam in a direction of the normal line of said base plane, and

a light receiving unit attaching step of fixing a light receiving unit at said resin member.

Claim 8 (original): The fabrication method of a semiconductor laser package according to claim 7, wherein said resin member molding step includes the step of arranging said island member and said lead in a same resin molding die and effect resin molding.

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Claim 9 (original): The fabrication method of a semiconductor laser package according to claim 7, further comprising an island member formation step of forming said island member by cold forging.

Claim 10 (currently amended): The fabrication method of a semiconductor laser package according to claim 7, wherein said leads are lead is formed by shaping through press-working, and applying a bending process.

Claim 11 (original): An optical pick up apparatus comprising a semiconductor laser package defined in claim 1, and a lens, wherein said lens is fixed so that a focal point substantially matches a light emitting point of said laser chip.

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